EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	2714	257/700	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/19 15:56
L4	0	257/23.079	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/19 15:56
L5	0	257/23.171	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/19 15:56
S1	7	"6664632" or "6445001"	USPAT	OR	OFF	2004/06/27 19:02
S2	2702	257/773	USPAT	OR	ON	2004/06/27 19:02
S3	1059	257/773 and (solder or BGA or grid)	USPAT	OR	ON	2004/06/27 19:02
S4	1188	257/773 and (solder or BGA or grid or ball or bump)	USPAT	OR	ON	2004/06/27 20:12
S5	22968	(semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) and pad and (lines or layers) and circuits	USPAT	OR	ON	2004/06/27 20:14
S6	11003	((semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) and pad and (lines or layers) and circuits) and "257"/$.ccls.	USPAT	OR	ON	2004/06/27 20:14
S7	332	(semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) and pad and (redistribution or rewir$3 or redistribut$3) with (lines or layers) and circuits	USPAT	OR	ON	2004/06/27 21:34
S8	748	(semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) and pad and (redistribution or rewir$3 or redistribut$3) and circuits	USPAT	OR	ON	2004/06/27 22:56

EAST Search History

S9	416	((semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) and pad and (redistribution or rewir$3 or redistribut$3) and circuits) not ((semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) and pad and (redistribution or rewir$3 or redistribut$3) with (lines or layers) and circuits)	USPAT	OR	ON	2004/06/27 21:35
S10	1	"5400950".PN.	USPAT	OR	OFF	2004/06/27 22:30
S11	1	"5677575".PN.	USPAT	OR	OFF	2004/06/27 22:30
S12	1	"5731636".PN.	USPAT	OR	OFF	2004/06/27 22:30
S13	1	"5773882".PN.	USPAT	OR	OFF	2004/06/27 22:30
S14	1	"5814891".PN.	USPAT	OR	OFF	2004/06/27 22:31
S15	1	"5841194".PN.	USPAT	OR	OFF	2004/06/27 22:32
S16	1	"5909058".PN.	USPAT	OR	OFF	2004/06/27 22:32
S17	1	"6060775".PN.	USPAT	OR	OFF	2004/06/27 22:32
S18	1	"5397921".PN.	USPAT	OR	OFF	2004/06/27 22:39
S19	1	"5409865".PN.	USPAT	OR	OFF	2004/06/27 22:39
S20	1	"5646828".PN.	USPAT	OR	OFF	2004/06/27 22:39
S21	1	"6163458".PN.	USPAT	OR	OFF	2004/06/27 22:39
S22	1	"6287893".PN.	USPAT	OR	OFF	2004/06/27 22:39
S23	1	"4462534".PN.	USPAT	OR	OFF	2004/06/27 22:41
S24	1	"5024372".PN.	USPAT	OR	OFF	2004/06/27 22:41
S25	1	"5220200".PN.	USPAT	OR	OFF	2004/06/27 22:41
S26	1	"5261593".PN.	USPAT	OR	OFF	2004/06/27 22:41
S27	1	"5293067".PN.	USPAT	OR	OFF	2004/06/27 22:41
S28	1	"5346861".PN.	USPAT	OR	OFF	2004/06/27 22:41
S29	1	"5388327".PN.	USPAT	OR	OFF	2004/06/27 22:42
S30	1	"5455390".PN.	USPAT	OR	OFF	2004/06/27 22:42
S31	1	"5504277".PN.	USPAT	OR	OFF	2004/06/27 22:42
S32	1	"5539153".PN.	USPAT	OR	OFF	2004/06/27 22:42
S33	1	"5541450".PN.	USPAT	OR	OFF	2004/06/27 22:42
S34	1	"5547740".PN.	USPAT	OR	OFF	2004/06/27 22:42
S35	1	"5564617".PN.	USPAT	OR	OFF	2004/06/27 22:43
S36	1	"5604379".PN.	USPAT	OR	OFF	2004/06/27 22:43
S37	1	"5608262".PN.	USPAT	OR	OFF	2004/06/27 22:43
S38	1	"5701032".PN.	USPAT	OR	OFF	2004/06/27 22:43

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S39	1	"5736456".PN.	USPAT	OR	OFF	2004/06/27 22:43
S40	1	"5777391".PN.	USPAT	OR	OFF	2004/06/27 22:44
S41	1	"5814894".PN.	USPAT	OR	OFF	2004/06/27 22:44
S42	1	"6287893".PN.	USPAT	OR	OFF	2004/06/27 22:45
S43	1	"4626889".PN.	USPAT	OR	OFF	2004/06/27 22:55
S44	1	"4833521".PN.	USPAT	OR	OFF	2004/06/27 22:55
S45	1	"5623628".PN.	USPAT	OR	OFF	2004/06/27 22:55
S46	1	"5945886".PN.	USPAT	OR	OFF	2004/06/27 22:55
S47	1	"5950304".PN.	USPAT	OR	OFF	2004/06/27 22:55
S48	1	"5983089".PN.	USPAT	OR	OFF	2004/06/27 22:55
S49	1	"6018196".PN.	USPAT	OR	OFF	2004/06/27 22:55
S50	1	"6020220".PN.	USPAT	OR	OFF	2004/06/27 22:55
S51	1	"6020637".PN.	USPAT	OR	OFF	2004/06/27 22:55
S52	1	"6048753".PN.	USPAT	OR	OFF	2004/06/27 22:55
S53	1	"6121815".PN.	USPAT	OR	OFF	2004/06/27 22:56
S54	1	"6114751".PN.	USPAT	OR	OFF	2004/06/27 22:56
S55	3388	257/778	USPAT	OR	OFF	2004/06/27 22:56
S56	2295	257/778 and (semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) and pad and circuits	USPAT	OR	ON	2004/06/27 23:16
S57	320	257/778 and (solder or BGA or grid or ball or bump) and pad and (outer or peripheral or edge) near (pad or contact or terminal) and circuits	USPAT	OR	ON	2004/06/27 22:58
S58	347	257/778 and (solder or BGA or grid or ball or bump) and pad and (outer or peripheral or edge) near (pad or contact or terminal or electrode) and circuits	USPAT	OR	ON	2004/06/27 23:27
S59	1952	(257/778 and (semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) and pad and circuits) not (257/778 and (solder or BGA or grid or ball or bump) and pad and (outer or peripheral or edge) near (pad or contact or terminal or electrode) and circuits)	USPAT	OR	ON	2004/06/27 23:17
S60	1	"5371404".PN.	USPAT	OR	OFF	2004/06/27 23:18
S61	1	"5422513".PN.	USPAT	OR	OFF	2004/06/27 23:19
S62	1	"6201701".PN.	USPAT	OR	OFF	2004/06/27 23:19

S63	1	"6271469".PN.	USPAT	OR	OFF	2004/06/27 23:19
S64	1	"6492723".PN.	USPAT	OR	OFF	2004/06/27 23:21
S65	1	"3809625".PN.	USPAT	OR	OFF	2004/06/27 23:51
S66	1	"4268849".PN.	USPAT	OR	OFF	2004/06/27 23:51
S67	1	"5046161".PN.	USPAT	OR	OFF	2004/06/27 23:51
S68	1	"5329423".PN.	USPAT	OR	OFF	2004/06/27 23:51
S69	1	"5789271".PN.	USPAT	OR	OFF	2004/06/27 23:52
S70	1	"5903058".PN.	USPAT	OR	OFF	2004/06/27 23:52
S71	1	"6054773".PN.	USPAT	OR	OFF	2004/06/27 23:52
S72	1	"6350668".PN.	USPAT	OR	OFF	2004/06/27 23:53
S73	1	"6384481".PN.	USPAT	OR	OFF	2004/06/27 23:53
S74	1	"6249044".PN.	USPAT	OR	OFF	2004/06/27 23:53
S75	1	"6258705".PN.	USPAT	OR	OFF	2004/06/27 23:53
S76	1	"5046161".PN.	USPAT	OR	OFF	2004/06/28 00:19
S77	1	"5600180".PN.	USPAT	OR	OFF	2004/06/28 00:19
S78	1	"5629564".PN.	USPAT	OR	OFF	2004/06/28 00:19
S79	623	(semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) with via and pad and (outer or peripheral or edge) near (pad or contact or terminal or electrode) and circuits	USPAT	OR	ON	2004/06/28 04:17
S80	2124	(semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) with via and pad and (outer or peripheral or edge) with (pad or contact or terminal or electrode) and circuits	USPAT	OR	ON	2004/06/28 01:55
S81	1501	((semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) with via and pad and (outer or peripheral or edge) with (pad or contact or terminal or electrode) and circuits) not ((semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) with via and pad and (outer or peripheral or edge) near (pad or contact or terminal or electrode) and circuits)	USPAT	OR	ON	2004/06/28 03:42
S82	21	"4521449"	USPAT	OR	ON	2004/06/28 03:45
S83	10	"4562513"	USPAT	OR	ON	2004/06/28 03:47
S84	112	"5477933"	USPAT	OR	ON	2004/06/28 03:47

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S85	1	"3978248".PN.	USPAT	OR	OFF	2004/06/28 04:13
S86	147	(semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) with (hole or via) and (pad or electrode) and (outermost or perimet$3) near (pad or contact or terminal or electrode) and circuits	USPAT	OR	ON	2004/06/28 05:31
S87	727	(semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) with (hole) and (pad or electrode) and (outer or perimet$3 or peripheral or edge) near (pad or contact or terminal or electrode) and circuits	USPAT	OR	ON	2004/06/28 06:45
S88	675	(semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) with (opening or open) and (pad or electrode) and (outer or perimet$3 or peripheral or edge) near (pad or contact or terminal or electrode) and circuits	USPAT	OR	ON	2004/06/28 06:46
S89	1390	257/734	USPAT	OR	OFF	2004/06/28 11:17
S90	9	wafer near holder with fixture	USPAT	OR	OFF	2004/06/28 11:29
S91	2550	wafer near holder	USPAT	OR	OFF	2004/06/28 11:21
S92	36	wafer near holding with fixture	USPAT	OR	OFF	2004/06/28 11:30
S93	7	wafer near holding with fixture and wafer with rotation	USPAT	OR	OFF	2004/06/28 11:31
S94	4	wafer near holding with fixture and wafer with rotating	USPAT	OR	OFF	2004/06/28 11:32
S95	21	wafer near hold$3 with fixture and wafer with rotat$3 and plat$3 with wafer	USPAT	OR	OFF	2004/06/28 11:35
S96	5	wafer near hold$3 with fixture and wafer with rotat$3 and plat$3 with wafer and wafer with etch$3	USPAT	OR	OFF	2004/06/28 11:35
S97	11437	(semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) with (hole or via) and (pad or contact or terminal or electrode) and circuits	USPAT	OR	ON	2004/06/28 13:34
S98	5672	(semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) with (hole or via) with (pad or contact or terminal or electrode) and circuits	USPAT	OR	ON	2004/06/28 13:35

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S99	3186	((semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) with (hole or via) with (pad or contact or terminal or electrode) and circuits) and "257"/$.ccls.	USPAT	OR	ON	2004/06/28 13:35
S100	3601	(semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) with (via) with (pad or contact or terminal or electrode) and circuits	USPAT	OR	ON	2004/06/28 13:35
S101	2239	((semiconductor or die or chip or IC) and (solder or BGA or grid or ball or bump) with (via) with (pad or contact or terminal or electrode) and circuits) and "257"/$.ccls.	USPAT	OR	ON	2004/06/28 13:39
S103	804	257/688	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/01 12:25
S104	314	(semiconductor or die or chip or IC) and (inner or internal or inside) near (pad or terminal or contact) with connect$3 with (outer or outside) near (pad or terminal or contact)	USPAT; JPO	OR	ON	2005/03/01 13:11
S105	402	(semiconductor or die or chip or IC) and (interposer or interconnect$3 or redistribut$3) and (inner or internal or inside) near (pad or terminal or contact) same (outer or outside) near (pad or terminal or contact)	USPAT; JPO	OR	ON	2005/03/01 14:44
S106	147120	(semiconductor or die or chip or IC) and (interposer or interconnect$3 or redistribut$3)	USPAT; JPO	OR	ON	2005/03/01 14:44
S107	58957	(semiconductor or die or chip or IC) same (interposer or interconnect$3 or redistribut$3)	USPAT; JPO	OR	ON	2005/03/01 14:44
S108	3682	S107 and (inner or internal or inside) with pad	USPAT; JPO	OR	ON	2005/03/01 14:45
S109	636	S107 and (inner or internal or inside) with pad same (peripheral or edge) with pad	USPAT; JPO	OR	ON	2005/03/01 14:47

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S110	473	S107 and (inner or internal or inside) with pad with (peripheral or edge) with pad	USPAT; JPO	OR	ON	2005/03/01 14:49
S111	163	S109 not S110	USPAT; JPO	OR	ON	2005/03/01 16:26
S112	2376	257/777	USPAT; JPO	OR	ON	2005/03/01 16:27
S113	1012	257/781	USPAT; JPO	OR	ON	2005/03/01 16:27
S114	105	257/781	US-PGPUB; USOCR; EPO; DERWENT; IBM_TDB	OR	OFF	2005/03/01 20:14
S115	1	"6437434".pn.	US-PGPUB; USOCR; EPO; DERWENT; IBM_TDB	OR	OFF	2005/03/01 20:12
S116	1	"6437434"	US-PGPUB; USOCR; EPO; DERWENT; IBM_TDB	OR	OFF	2005/03/01 20:12
S117	0	"6437434" and (power or ground or clock)	US-PGPUB; USOCR; EPO; DERWENT; IBM_TDB	OR	OFF	2005/03/01 20:12
S118	1	"6437434" and (power or ground or clock)	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	OFF	2005/03/01 20:14
S119	195	257/780	US-PGPUB; USOCR; EPO; DERWENT; IBM_TDB	OR	OFF	2005/03/01 20:14
S120	2123	257/780	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/01 20:34

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S12 1	804	257/688	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/02 17:59
S12 2	1	"6445001".pn. and barrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/02 17:52
S12 3	367	257/733	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/02 19:00
S12 4	3	barrier with extension with pad same (semiconductor or chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/02 19:03
S12 5	1	barrier with extension with pad same (semiconductor or chip or die)	USPAT	OR	OFF	2005/03/02 19:03
S12 6	0	barrier with extension with pad same (semiconductor or chip or die) and "5886414"	USPAT	OR	OFF	2005/03/02 19:03
S12 7	1	barrier with extension with pad and (semiconductor or chip or die) and "5886414"	USPAT	OR	OFF	2005/03/02 19:06
S12 8	1	"6686659"	USPAT	OR	OFF	2005/03/02 22:38
S12 9	1	"6069793".pn. and (encapsulat$3 or mold$3)	USPAT	OR	OFF	2005/03/02 22:39
S13 0	1	"6069793".pn. and (encapsulat$3 or mold$3) with bare	USPAT	OR	OFF	2005/03/02 22:39
S13 1	499	floating near terminal	USPAT	OR	OFF	2005/08/15 13:42
S13 2	0	floating near terminal with means	USPAT	OR	OFF	2005/08/15 13:43
S13 3	6	floating near terminal with defin$3	USPAT	OR	OFF	2005/08/15 13:44
S13 4	0	floating near terminal with none near floating near terminal	USPAT	OR	OFF	2005/08/15 13:45

S13 5	0	floating near terminal with none-floating near terminal	USPAT	OR	OFF	2005/08/15 13:45
S13 6	2	floating near terminal with non-floating near terminal	USPAT	OR	OFF	2005/08/15 14:20
S13 7	1	"20040145061"	US-PGPUB; USPAT	OR	OFF	2005/08/15 14:21
S13 8	37869	RF near signal	US-PGPUB; USPAT	OR	OFF	2005/08/15 14:21
S13 9	122	RF near signal with pad	USPAT	OR	OFF	2005/08/15 15:25
S14 0	1134	257/781	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/15 15:35
S14 1	2166	257/780	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/15 15:35
S14 2	38763	"778"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/31 19:23
S14 3	4956	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/31 19:31
S14 4	1695	257/779	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/31 20:19
S14 5	2312	257/780	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/31 20:45

S14 6	1204	257/781	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/31 20:54
S14 7	2579	257/700	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/31 21:23
S14 8	0	"630151054"	JPO	OR	OFF	2006/01/31 21:23
S14 9	0	"0630151054"	JPO	OR	OFF	2006/01/31 21:23